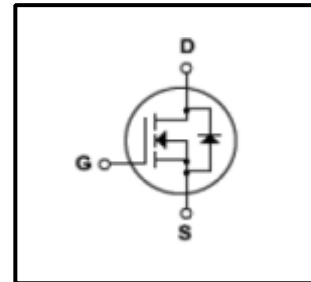


Silicon N-Channel MOSFET

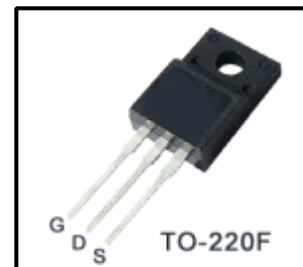
Features

- 20A,600V, $R_{DS(on)}$ (Max0.39 Ω)@ $V_{GS}=10V$
- Ultra-low Gate charge(Typical 50nC)
- Fast Switching Capability
- 100%Avalanche Tested
- Maximum Junction Temperature Range(150 $^{\circ}C$)



General Description

This Power MOSFET is produced using Winsemi's advanced planar stripe, VDMOS technology. This latest technology has been especially designed to minimize on-state resistance, have a high rugged avalanche characteristics. This device is specially well suited for AC-DC switching power supplies, DC-DC power converters, high voltage H-bridge motor drive PWM.



Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V_{DSS}	Drain Source Voltage	600	V
I_D	Continuous Drain Current(@ $T_c=25^{\circ}C$)	20*	A
	Continuous Drain Current(@ $T_c=100^{\circ}C$)	12.5*	A
I_{DM}	Drain Current Pulsed (Note1)	20*	A
V_{GS}	Gate to Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy (Note2)	450	mJ
I_{AR}	Avalanche Current (Note1)	20	A
E_{AR}	Repetitive Avalanche Energy (Note1)	20.7	mJ
dv/dt	Peak Diode Recovery dv /dt (Note3)	50	V/ ns
P_D	Total Power Dissipation(@ $T_c=25^{\circ}C$)	55	W
	-Derate above 25 $^{\circ}C$	0.31	W/ $^{\circ}C$
T_J, T_{stg}	Junction and Storage Temperature	-55~150	$^{\circ}C$
T_L	Channel Temperature	300	$^{\circ}C$

*Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	Value			Units
		Min	Typ	Max	
R_{QJC}	Thermal Resistance , Junction -to -Case	-	-	2.27	$^{\circ}C/W$
R_{QJA}	Thermal Resistance , Junction -to -Ambient	-	-	62.5	$^{\circ}C/W$

Electrical Characteristics(Tc=25°C)

Characteristics	Symbol	Test Condition	Min	Type	Max	Unit	
Gate leakage current	I_{GSS}	$V_{GS}=\pm 30V, V_{DS}=0V$	-	-	± 100	nA	
Gate-source breakdown voltage	$V_{(BR)GSS}$	$I_G=\pm 10 \mu A, V_{DS}=0V$	± 30	-	-	V	
Drain cut -off current	I_{DSS}	$V_{DS}=600V, V_{GS}=0V$	-	-	1	μA	
		$V_{DS}=480V, T_J=125^\circ C$	-	-	10	μA	
Drain -source breakdown voltage	$V_{(BR)DSS}$	$I_D=250\mu A, V_{GS}=0V$	600	-	-	V	
Breakdown voltage Temperature coefficient	$\Delta BV_{DSS}/\Delta T_J$	$I_D=250\mu A$, Referenced to 25°C	-	0.5	-	V/°C	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	3	-	5	V	
Drain -source ON resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=10A$	-	0.35	0.39	Ω	
Forward Transconductance	g_{fs}	$V_{DS}=40V, I_D=10A$ (Note4)	-	18	-	S	
Input capacitance	C_{iss}	$V_{DS}=25V,$	-	2310	2920	pF	
Reverse transfer capacitance	C_{rss}	$V_{GS}=0V,$	-	85	120		
Output capacitance	C_{oss}	$f=1MHz$	-	1270	1660		
Switching time	Turn-on Rise time	t_r	$V_{DD}=250V$		-	130	ns
	Turn-on delay time	$t_d(on)$	$I_D=20A$		-	60	
	Turn-on Fall time	t_f	$R_G=25\Omega$ (Note4,5)		-	70	
	Turn-off delay time	$t_d(off)$			-	220	
Total gate charge(gate-source plus gate-drain)	Q_g	$V_{DS}=480V,$ $V_{GS}=10V,$	-	50	80	nC	
Gate-source charge	Q_{gs}	$I_D=20A$ (Note4,5)	-	15	-		
Gate-drain("miller") Charge	Q_{gd}		-	23	-		

Source-Drain Ratings and Characteristics(Ta=25°C)

Characteristics	Symbol	Test Condition	Min	Type	Max	Unit
Continuous drain reverse current	I_{DR}	-	-	-	20	A
Forward voltage(diode)	V_{DSF}	$I_S=20A, V_{GS}=0V$	-	-	1.4	V
Reverse recovery time	t_{rr}	$I_{DR}=20A, V_{GS}=0V,$	-	460	-	ns
Reverse recovery charge	Q_{rr}	$dI_{DR} / dt = 100 A / \mu s$	-	5.1	-	μC

Note 1.Pulse width limited by maximum junction temperature

2.L=5.0mH, $I_{AS}=20A, V_{DD}=50V, R_G=25\Omega$, Starting $T_J=25^\circ C$

3. $I_{SD}\leq 20A, di/dt\leq 200a/\mu s, V_{DD}\leq BV_{DSS}$, Starting $T_J=25^\circ C$

4.Pulse Test:Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

5. Essentially independent of operating temperature.

This transistor is an electrostatic sensitive device

Please handle with caution

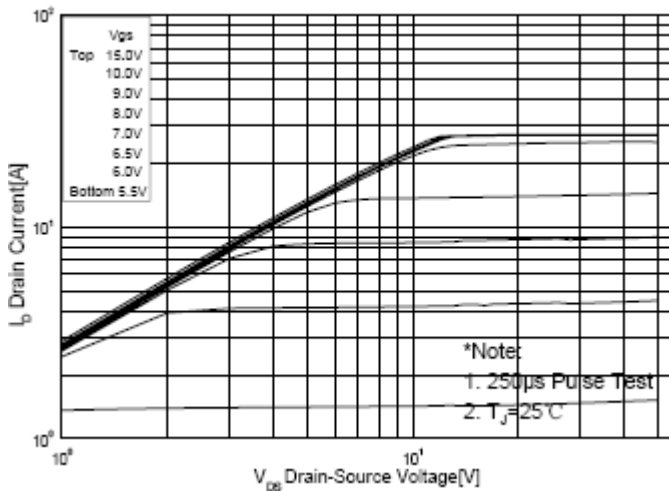


Fig.1 On Region Characteristics

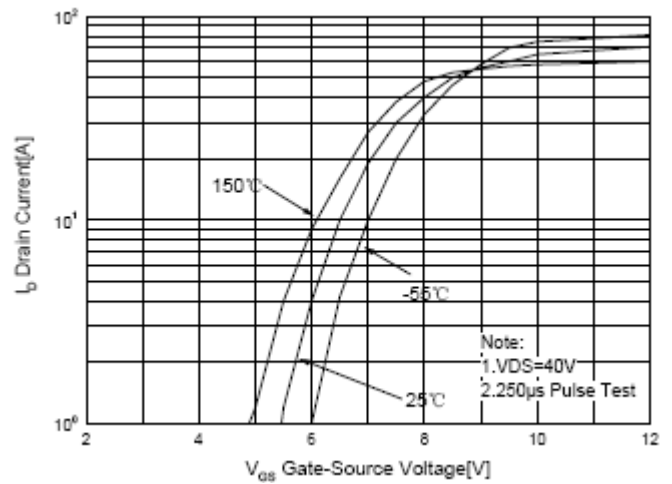


Fig.2 Transfer Characteristics

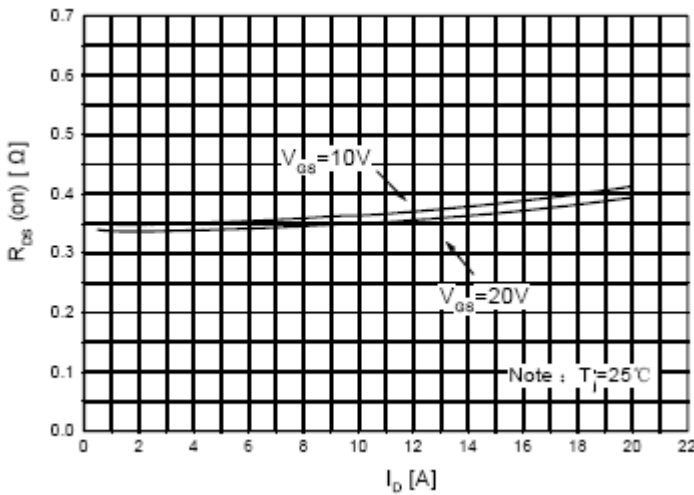


Fig.3 On-Resistance Variation vs Drain current and Gate Voltage

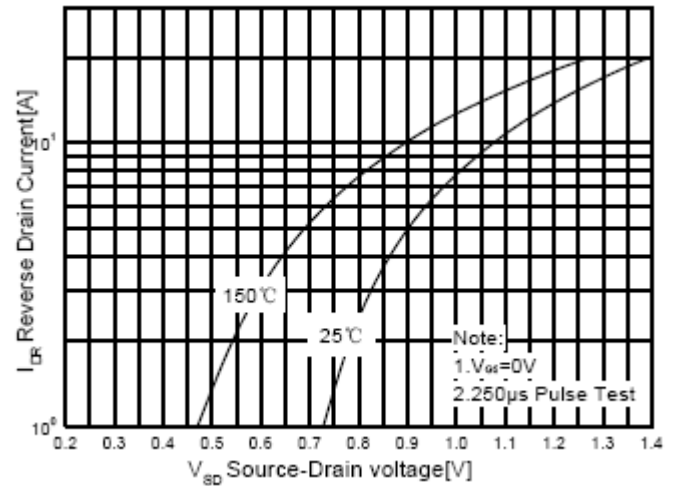


Fig.4 Body Diode Forward voltage Variation with Source Current And Temperature

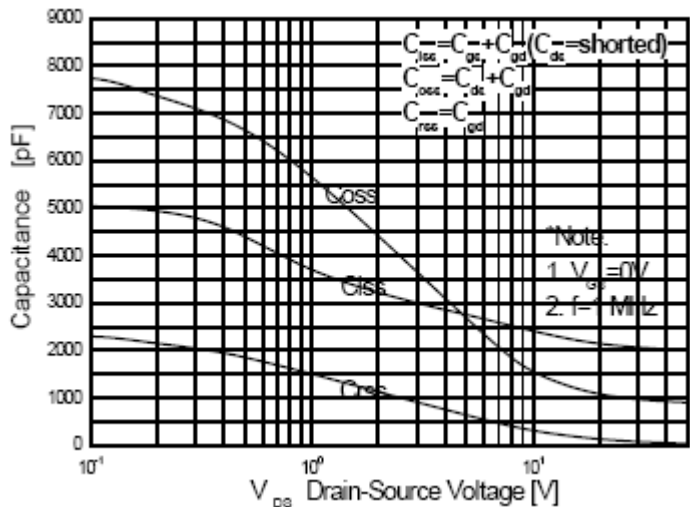


Fig.5 Capacitance Characteristics

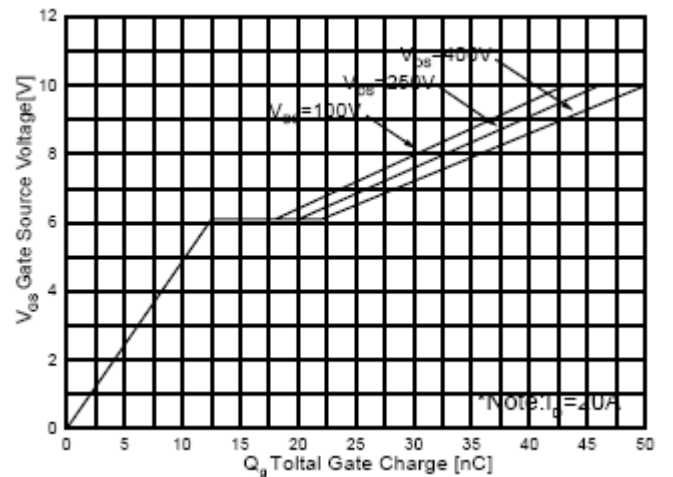


Fig.6 Gate Charge Characteristics

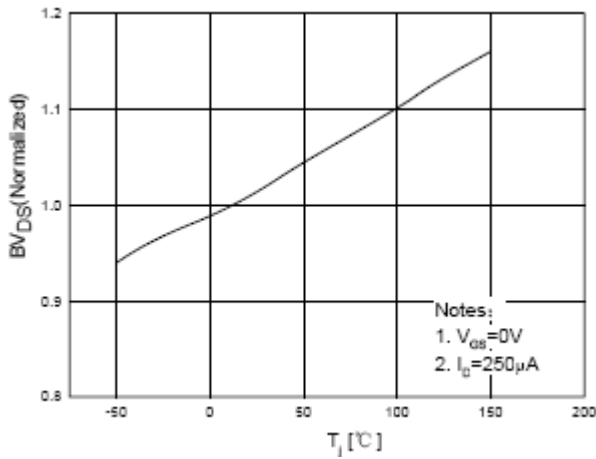


Fig.7 Breakdown Voltage Variation vs. Temperature

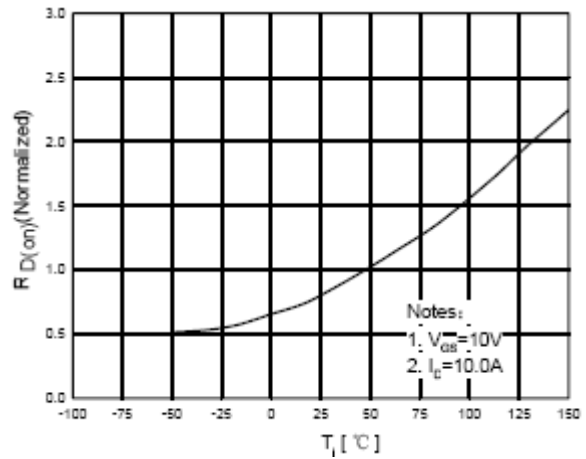


Fig.8 On-Resistance Variation vs. Temperature

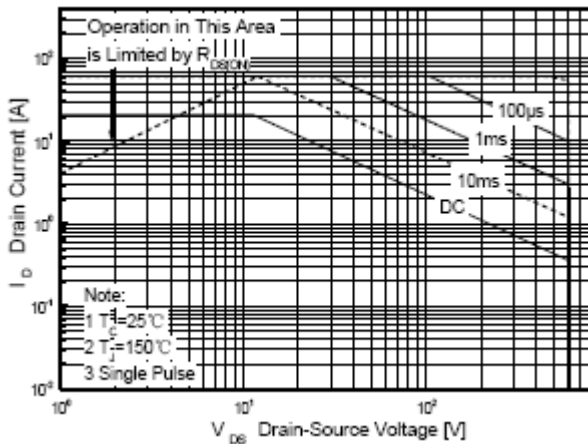


Fig.9 Maximum Safe Operation Area

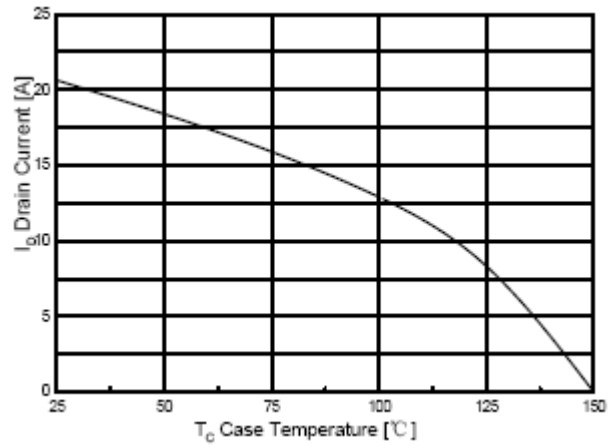


Fig.10 Maximum Drain Current vs Case temperature

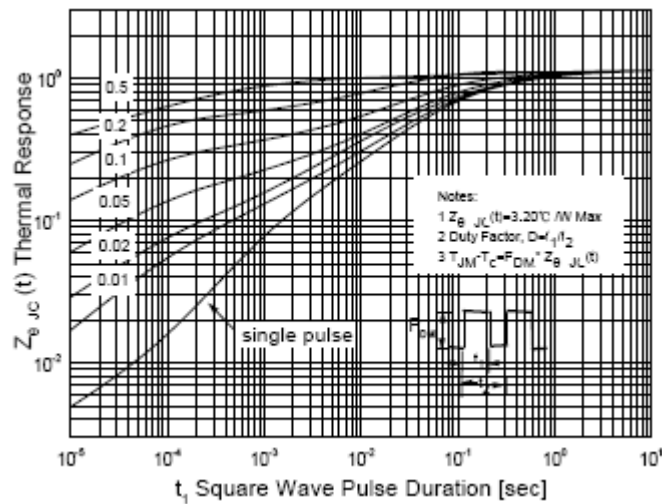


Fig.11 Transient thermal Response Curve

TO-220F Package Dimension

